

3. The circuit board of Claim 2, wherein the contact comprises a layer of copper plated with gold.

4. The circuit board of Claim 1, further comprising a dam inside the inner periphery of the slit.

5. The circuit board of Claim 1, wherein the base board is made of a glass-epoxy material.

6. The circuit board of Claim 1, wherein the base board includes a sprocket hole along at least one of the edges thereof.

7. The circuit board of Claim 1, wherein the base board includes a position hole along one of the edges thereof.

8. The circuit board of Claim 2, further comprising:
a semiconductor chip attached to an upper surface of the unit board, the chip having a connection pad on an upper surface thereof; and,
a conductive wire having opposite ends, each bonded to a respective one of the bonding pad on the unit board and the connection pad on the chip.

9. The circuit board of Claim 8, further comprising an encapsulant formed on the top surface of the unit board and encapsulating a region including the chip, the conductive wire, the bonding pad, and the connection pad.